

of the contacts on said first semiconductor chip through said lead portions and said first bonding wires.

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57. The assembly as claimed in claim 56, further comprising a dielectric encapsulant covering at least a portion of said first bonding wires.

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58. The assembly as claimed in claim 57, wherein the encapsulant is compliant.

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59. The assembly as claimed in claim 58, further comprising a dielectric encapsulant covering at least a portion of the electrical connections between the contacts on the chip and the terminals of said first backing element.

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60. The assembly as claimed in claim 59, wherein the encapsulant is compliant.

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61. The assembly as claimed in claim 60, wherein said terminals of said backing element are solder-bonded to said contact pads of said substrate.

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62. The assembly as claimed in any of claims 57 through 61, wherein said substrate is a circuit panel.

REMARKS

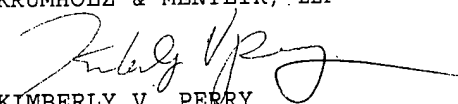
The present preliminary amendment presents new claims 2-62, amends the title and the abstract to more accurately describe the scope of the presently claimed invention, and amends the specification to correct

typographical errors and to reference prior copending nonprovisional applications under 37 C.F.R. 1.78 (a)(2). The present preliminary amendment should be entered because it is fully supported by the specification and introduces no new matter.

The new claims are believed presently allowable and do not introduce new matter. Accordingly, Applicant respectfully requests entry of this amendment and earnestly solicits allowance of all claims.

Respectfully submitted,

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